

Zhen Ding Held 2025 AGM, Advancing Structural Transformation to Navigate AI Disruption and Global Supply Chain Realignment

Zhen Ding Technology Holding Limited (Ticker: 4958), a global leading PCB manufacturer, held its 2025 Annual General Shareholders' Meeting (AGM) today. In response to the rapid rise of artificial intelligence (AI) and the growing impact of geopolitical tensions driving global supply chain restructuring, Chairman Charles Shen emphasized that AI remains in its early stages of development, and it will inevitably reshape and redefine the industrial landscape, presenting the PCB industry with unprecedented opportunities for technological innovation and new applications. As the world's largest PCB manufacturer, Zhen Ding recognizes the critical importance of this industrial transformation and has embarked on a company-wide structural overhaul and digital transformation to lay a solid foundation for its long-term growth strategy over the next decade.

Chairman Shen highlighted that Zhen Ding's structural transformation focuses on several key areas. First, earlier this year, the company appointed Dr. Chen-Fu Chien as General Manager to lead its progress across five key pillars, including smart manufacturing, industrial engineering, AI empowerment, semiconductor industry engagement, and industry-academia collaboration. Looking ahead, Zhen Ding's leadership will be anchored by a well-balanced "iron triangle" team comprising Chairman and Group Chief Strategy Officer Charles Shen, General Manager Chen-Fu Chien, and Chief Operating Officer D.J. Lee. This management structure is designed to strengthen operational agility and accelerate the company's ongoing transformation.

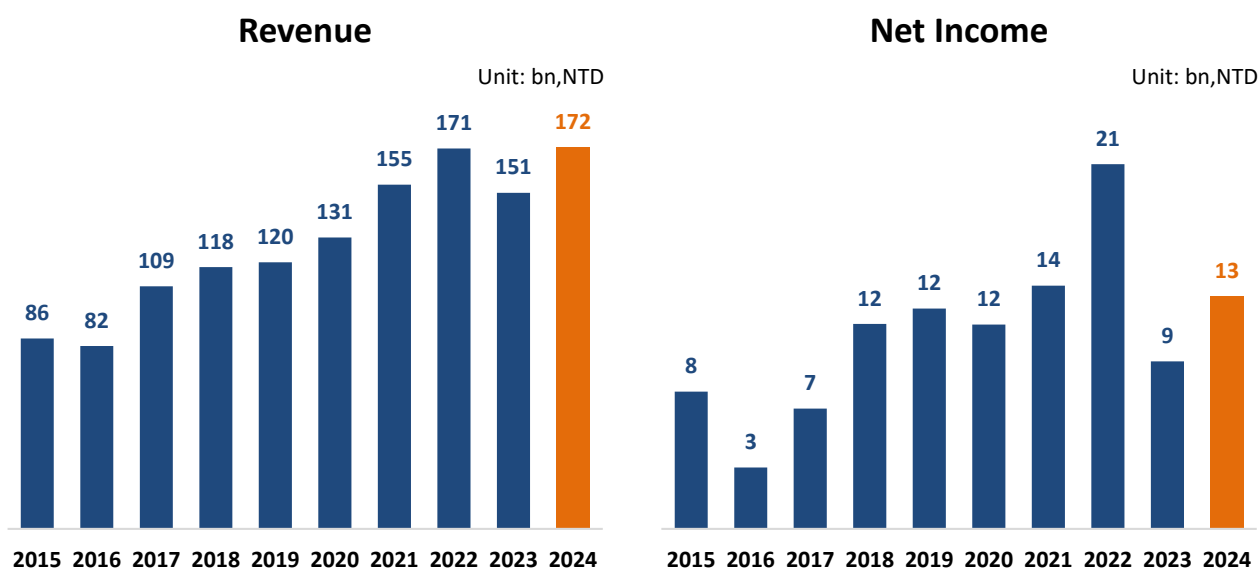
Second, Zhen Ding is actively expanding its global manufacturing footprint, establishing high-end production capacities in Mainland China, Thailand, and Kaohsiung to meet the trend of supply chain "localization" and "regionalization". Third, the company is accelerating the implementation of smart manufacturing to enhance operational efficiency and strengthen the competitive advantages of its global production sites. Fourth, in response to the rapid growth of AI applications, the company is increasing its R&D investment and partnering with leading global customers to co-develop next-generation AI products, ensuring Zhen Ding remains a critical player in the evolving AI supply chain. Fifth, it is making strategic investments in global talent development. In May, Zhen Ding signed a MOU with the Asian Institute of Technology (AIT), focusing on three key areas: talent development, technology collaboration, and industry-academia integration. This partnership supports the company's long-term strategy for globalization and technological advancement.

Looking ahead to 2025, Chairman Shen emphasized that Zhen Ding is on track to achieve record-high revenue this year, with growth across all four major applications. This momentum underscores the strong competitiveness of the company's diversified product portfolio across key application markets.

Despite a challenging macroeconomic environment, Zhen Ding continues to demonstrate operational resilience, supported by its industry-leading net cash position and robust financial structure. These strengths provide a solid foundation for sustained expansion and long-term investment. More strategically, the company's ongoing "One ZDT" initiative and structural transformation are expected to yield tangible results over the next three years. Zhen Ding is fully confident to unlock substantial revenue and profit growth over the mid-to long term.

Zhen Ding currently holds a leading position in edge AI applications. Its smart glasses application is expected to achieve several-fold growth this year, while foldable smartphones are poised to gain renewed momentum in 2026. At the same time, the company is making meaningful progress across several high-growth applications, including IC substrates, AI servers, optical, and automotive electronics, where it has secured orders for advanced and next-generation products from key customers. Construction of its new plant in Prachinburi, Thailand, is progressing smoothly, with small-scale mass production scheduled to begin in the second half of this year. This site will complement existing production bases in Mainland China and Kaohsiung, creating a more agile and resilient global supply chain.

Zhen Ding will continue to execute its core strategy of "Building a Global Presence, Driving High-End Development." It will accelerate new capacity ramp-up, upgrade its product portfolio, combine manufacturing excellence with innovation in R&D, actively attract top-tier talent, and deepen collaboration with global customers. Through these efforts, the company is committed to becoming a key enabler in AI-driven innovation and the evolution of the PCB industry.



About Zhen Ding Technology Holding Limited

Zhen Ding Technology Holding Limited (Taiwan Stock Exchange: 4958) specializes in the research, development, production, and sales of a diversified range of products, including flexible printed circuit board (FPC) and surface mount assembly (SMA), substrate-like PCBs (SLP), high-density interconnect (HDI) PCBs, high-layer-count and high-density (HLC-HDI) boards, multilayer rigid printed circuit boards (RPCB) and IC substrates (ICS). These products are widely used in end products such as computer information, consumer electronics, communications networks, automotive electronics, AI server high-speed computing, optical module and medical applications. The company offers professional one-stop shopping, full-solution services to customer worldwide. According to Prismark's global PCB industry rankings by revenue, Zhen Ding has been ranked the world's largest PCB manufacturer for eight consecutive years, from 2017 to 2024. For more detailed information, please visit the company website: www.zdtco.com.

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